EPCDESIGNTOOL_LG-EM
Mechanical Die for Electromigration Testing

EPCDESIGNTOOL_LG-EM are sized equivalent to EPC device EPC2001C with die size 4.1 mm x 1.6 mm.

These devices have internal metal layers shorted for electromigration reliability testing.

Figure 1: Die Photo for EPCDESIGNTOOL_LG-EM

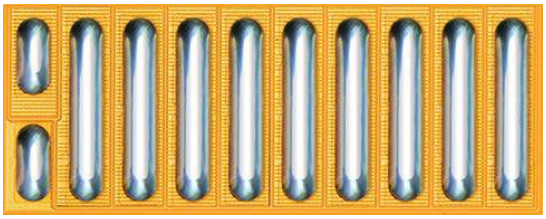
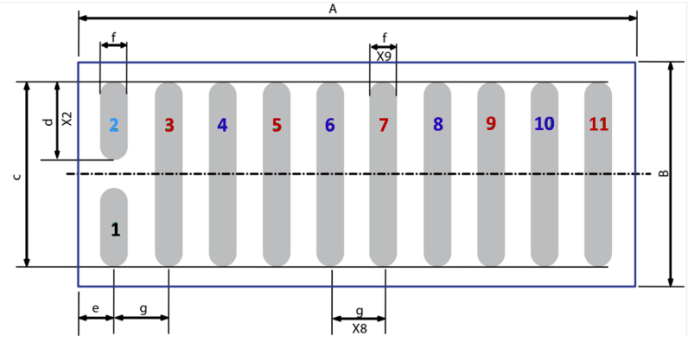


Figure 2: Die Outline (Solder Bar View)



DIM	MICROMETERS		
	MIN	Nominal	MAX
A	4075	4105	4135
B	1602	1632	1662
c	1379	1382	1385
d	577	580	583
e	235	250	265
f	195	200	205
g	400	400	400

Pad 1 is Gate;
Pads 3, 5, 7, 9, 11 are Drain
Pads 4, 6, 8, 10 are Source
Pad 2 is Substrate
NOTE: Drain and Source are internally shorted at Metal 1 to create a metal resistor

Figure 3: Side View

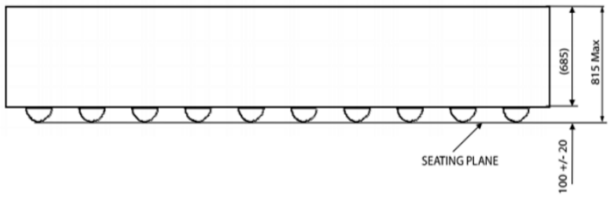
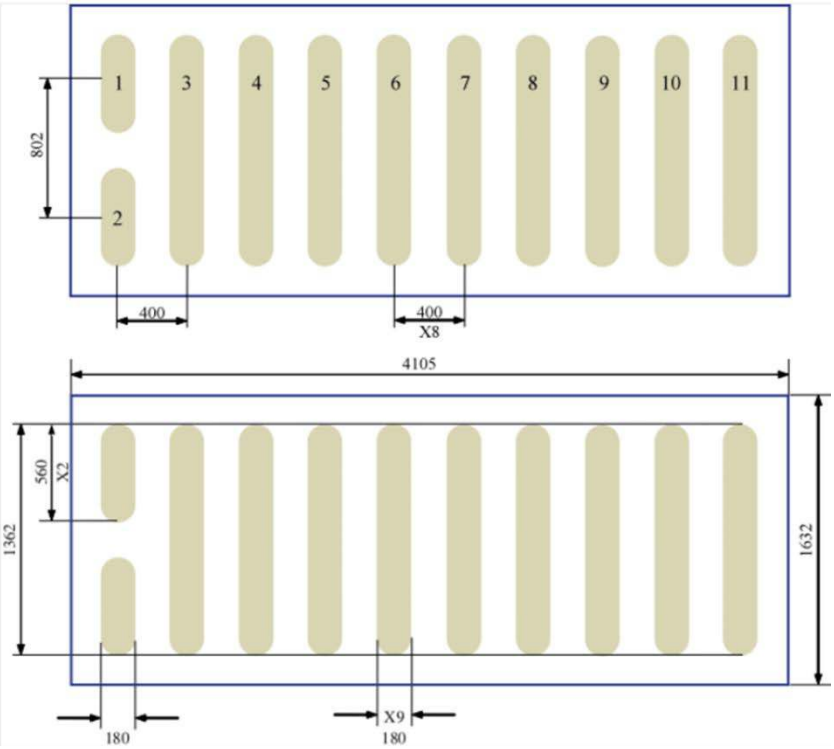


Figure 4: Recommended Land Pattern (units in µm)

Land pattern is solder mask defined. Solder mask opening is 180 µm. Recommended stencil should be 4mil (100 µm) thick, must be laser cut, Stencil opening can be per the bump drawing.



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Additional assembly resources available at epc-co.com/epc/DesignSupport/AssemblyResources.aspx